TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS

TIPD120: 3-Wire RTD Measurement System Reference Design, -200°C to 850°C

Item #	Quantity	Designator	Value	Description	Manufacturer	Part Number
1	8	C1, C4, C5, C7, C9, C10, C11, C13	0.1 µF	CAP CER 0.1UF 50V 10% X7R 0603	MuRata	GRM188R71H104KA93D
2	2	C2, C8	10 µF	CAP CER 10UF 25V 20% X7R 1210	TDK	C3225X7R1E106M250AC
3	2	C3, C6	0.01 µF	CAP CER 10000PF 25V 5% NP0 0603	TDK	C1608C0G1E103J080AA
4	1	C12	1 µF	CAP CER 1UF 25V 10% X7R 0603	Taiyo Yuden	TMK107B7105KA-T
5	2	C14, C16	3300 pF	CAP CER 3300PF 25V 5% NP0 0603	Samsung Electro-Mech	CL10C332JA8NNNC
6	1	C15	0.033 µF	CAP CER 0.033UF 25V 5% NP0 0805	TDK	C2012C0G1E333J125AA
7	2	C17, C19	1500 pF	CAP CER 1500PF 25V 5% NP0 0603	MuRata	GRM1885C1E152JA01D
8	1	C18	0.015 µF	CAP CER 0.015UF 25V 5% NP0 0603	Kemet	C0603C153J3GACTU
9	2	FB1, FB2		FERRITE CHIP 600 OHM 200MA 0603	MuRata	BLM18HG601SN1D
10	1	J1		CONN HEADER 3POS .100" SGL GOLD	Samtec, Inc.	TSW-103-07-G-S
11	1	J2		CONN SOCKET 50PIN .050 R/A SNGL	Mill-Max Manufacturing Corp.	851-43-050-20-001000
12	1	J3		TERMINAL BLOCK 3.5MM 3POS PCB	On Shore Technology Inc	ED555/3DS
13	1	R1	140k	RES, 140k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD07140KL
14	1	R2	78.7k	RES, 78.7k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD0778K7L
15	2	R3, R4	0	RES 0.0 OHM 1/10W JUMP 0603 SMD	Panasonic Electronic	ERJ-3GEY0R00V
16	2	R5, R7	9.09k	RES, 9.09k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-9091-B-T5
17	2	R8, R10	20 k	RES, 20.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-203-B-T5
18	1	R9	820	RES 820 OHM 1/8W .02% 0805	Susumu	RG2012V-821-P-T1
19	1	TP1		Test Point, TH, Compact, Red	Keystone	5005
20	1	TP2		Test Point, TH, Compact, Black	Keystone	5006
21	1	U1		IC REG LDO ADJ 0.15A 8MSO	Texas Instruments Inc	TPS7A4901DGNR
22	1	U2		IC 4BIT NON-INV TRANSLTR 14TSSOP	Texas Instruments Inc	TXS0104EPWR
23	1	U3		IC ADC 24BIT DEL/SIG LN 20TSSOP	Texas Instruments Inc	ADS1247IPW

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